



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-06-27
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Floriana San Biagio	Representative Title	AMG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section		Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement


Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	HDO7*0922BR6	A	BO2A	2016-06-27
Amount	UoM	Unit type	ST ECOPACK Grade	
80.00	mg	Each	ECOPACK® 3	
	Comment	ECOPACK® 3 is STMicroelectronics trade name for ROHS compliant device without use of any ROHS exemption and without Halogen nor Antimony		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
DSO	4.85x3.9x1.52	8	gull wing	
Comment	Package: 07 SO 08 .15 JEDEC; MDF valid for TS922IDT			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	Description

QueryList : REACH-20th June 2016				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	HDO7*09228R6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	1.346	mg	supplier	die	Silicon (Si)	7440-21-3		1.335	mg	991828	16688
				supplier	metallization	Aluminium (Al)	7429-90-5		0.005	mg	3715	63
				supplier	Passivation	Silicon Nitride	12033-89-5		0.003	mg	2229	38
				supplier	Passivation	Silicon Oxide	7631-86-9		0.003	mg	2229	38
Leadframe	Copper & its alloys	32.113	mg	supplier	alloy	Copper (Cu)	7440-50-8		31.133	mg	969483	389163
				supplier	alloy	Iron (Fe)	7439-89-6		0.732	mg	22795	9150
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.044	mg	1370	550
				supplier	alloy	Zinc (Zn)	7440-66-6		0.038	mg	1183	475
				supplier	metallization	Nickel (Ni)	7440-02-0		0.151	mg	4702	1888
				supplier	metallization	Palladium (Pd)	7440-05-3		0.005	mg	156	63
				supplier	metallization	Gold (Au)	7440-57-5		0.005	mg	156	63
				supplier	metallization	Silver (Ag)	7440-22-4		0.005	mg	156	63
Die attach	Other Organic Materials	0.521	mg	supplier	glue	Silver (Ag)	7440-22-4		0.457	mg	877159	5713
				supplier	glue	Isobornyl Methacrylate	7534-94-3		0.026	mg	49904	325
				supplier	glue	Urethane Methacrylate Resin	5888-33-5		0.026	mg	49904	325
				supplier	glue	Acrylate polymer	87320-05-6		0.010	mg	19194	125
				supplier	glue	Epoxy cyclohexylethyltrimethoxysilane	3388-04-3		0.001	mg	1919	13
				supplier	glue	tert-Butyl peroxy(2-ethyl)-hexanoate	3006-82-4		0.001	mg	1919	13
Bonding wires	Other inorganic materials	0.065	mg	supplier	wire	Copper (Cu)	7440-50-8		0.065	mg	1000000	813
Encapsulation	Other Organic Materials	45.955	mg	supplier	mold compound	Silica, vitreous	60676-86-0		39.796	mg	865978	497450
				supplier	mold compound	Epoxy Resin	Proprietary		3.447	mg	7508	43088
				supplier	mold compound	Phenol Resin	Proprietary		2.298	mg	50005	28725
				supplier	mold compound	Carbon black	1333-86-4		0.230	mg	5005	2875
				supplier	mold compound	Bismuth compound	7440-69-9		0.184	mg	4004	2300